

RF Q2™ SERIES QMS-RF, QFS-RF SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS-RF or www.samtec.com?QFS-RF

Insulator Material:
Liquid Crystal Polymer



Contact, Terminal & Ground Plane Material:
Phosphor Bronze

Plating:
Au over 50µ" (1,27µm) Ni
(Tin on Ground Plane Tail)

Current Rating:
Contact: 1.5A @ 30°C
Temperature Rise
Ground Plane: 7.2A @ 30°C
Temperature Rise

Voltage Rating:
300 VAC

Operating Temp:
-55°C to +125°C

RoHS Compliant:
Yes

Processing:

Max Processing Temp:
230°C for 60 seconds, or
260°C for 20 seconds 3x
Lead-Free Solderable:
Yes

SMT Lead Coplanarity:
(0,10mm) .004" max (026-078)

Board Stacking:
For applications requiring more than two connectors per board, contact ipg@samtec.com

QMS	NO. OF PINS PER ROW	05.75	PLATING OPTION	D	END OPTION
Mates with: QFS-RF		-L = 10µ" (0,25µm) Gold on Signal Pins, and Ground Plane (Gold flash on Signal Pin tails, Tin on Ground Plane tails)			-RF1 = 1 RF Plug per End -RF2 = 2 RF Plugs per End
-026, -052, -078 (52 total pins per bank)					

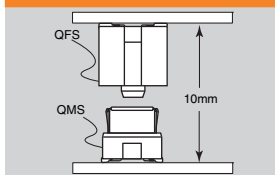
RF2 = No. of Banks x (21,34) .840 + (27,56) 1.085

RF1 = No. of Banks x (21,34) .840 + (14,86) .585

APPLICATION SPECIFIC OPTION

- Differential Pairs
- Call Samtec.

APPLICATION



QFS	NO. OF PINS PER ROW	04.25	PLATING OPTION	D	END OPTION
Mates with: QMS-RF		-L = 10µ" (0,25µm) Gold on Signal Pins, and Ground Plane (Gold flash on Signal Pin tails, Tin on Ground Plane tails)			-RF1 = 1 RF Jack per End -RF2 = 2 RF Jacks per End
-026, -052, -078 (52 total pins per bank)					

RF2 = No. of Banks x (21,34) .840 + (25,60) 1.008

RF1 = No. of Banks x (21,34) .840 + (14,30) .563

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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